

Remarks:

Reconsideration of the application is requested.

Claims 2, 4-6, 8 and 10-12 remain in the application. Claims 2, 4-6, 8 and 10-12 are subject to examination. Claims 2, 4-6, 8, and 10-12 have been amended. Claims 1, 3, 7 and 9 have been canceled to facilitate prosecution of the instant application.

In the third paragraph on page 2 of the above-identified Office action, claims 1, 3-5, 7 and 9-11 have been rejected as being fully anticipated by U.S. Patent No. (6,310,372) to Katayama et al. (hereinafter Katayama) under 35 U.S.C. § 102.

First, claims 1, 3, 7 and 9 have been canceled. Claims 4 and 10 are now independent claims incorporating the features of claims 1, 3 and 7, 9, respectively. In addition, claims 4 and 10 have been further amended with the feature that the insulator layer is disposed between the bulk silicon layer and the body silicon layer as shown in the figure of the drawing and as described on pages 5-6 of the specification of the instant application.

Katayama discloses a via which contacts an electrically conductive source region (e.g. body silicon layer) 6, 6A, provided with an n-type doping, through an insulating film 7.

A support substrate (bulk silicon layer) 3 supports a shield layer 4, and the shield layer 4 supports the body silicon layer 6, 6a. In contrast to amended claims 4 and 10 of the instant application, the feature of the insulating film 7 being disposed between the bulk silicon layer 3 and the body silicon layer 6 is not taught in the device structure according to Figs. 1 to 4 of Katayama.

Although the first insulating film 5 can be formed by SOI technology according to column 11, lines 32 to 35 of Katayama, the insulating film 7 cannot be identified with the insulating layer that separates the silicon body from the silicon bulk. It is only the first insulating film 5 that could be regarded as the boundary between the upper silicon body region and the bulk silicon substrate 3 containing the shielding layer 4.

There is no indication in Katayama that an electrically conductive shielding means might be disposed beneath the insulating layer 5 within the bulk silicon layer and electrically connected through the insulating layer 5 to conductors or device structures that are disposed within the body silicon layer 3. Although Katayama uses a shielding layer that is preferably formed of a metal, there is no electric conductor that connects the shielding layer with other electrically conductive parts of the device structure. The shielding layer is only described as a separate plate,

which is disposed above the substrate surface and covered with the electrically insulating material of layers 5 and 7.

Therefore, the features of amended claims 4 and 10 of the instant application of an electrically conductive shield is not believed to be anticipated by or obvious from Katayama.

In the sixth paragraph on page 2 of the above-identified Office Action, the Examiner noted that claims 2, 6, 8 and 12 are allowable. Claims 2, 6, 8 and 12 have been put in independent form. Please find enclosed a credit card authorization for \$600.00 for the three additional independent claims.

It is accordingly believed to be clear that none of the references, whether taken alone or in any combination, either show or suggest the features of claim 2, 4, 6, 8, 10 or 12. Claims 2, 4, 6, 8, 10 and 12 are, therefore, believed to be patentable over the art. The dependent claims are believed to be patentable as well because they all are ultimately dependent on claim 4 or 10.

In view of the foregoing, reconsideration and allowance of claims 2, 4-6, 8 and 10-12 are solicited.

If an extension of time for this paper is required, petition
for extension is herewith made.

Please charge any other fees that might be due with respect to
Sections 1.16 and 1.17 to the Deposit Account of Lerner and
Greenberg, P.A., No. 12-1099.

Respectfully submitted,



For Applicants

REL:kf

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February 2, 2005

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